

**IN THE SPECIFICATION:**

Please amend paragraph [0045] as follows:

[0045] Process (7)

First, a package 27, onto which CCD chip 15 is to be mounted, is prepared. The package 27 comprises a CCD chip mounting portion 27a and a protruding portion 27b, which is formed so as to oppose CCD chip mounting portion 27a, and has an electrode pad 29 on the surface of protruding portion 27b that opposes CCD chip mounting portion 27a. An opening 27c is formed at a position of CCD chip mounting portion 27a that opposes protruding portion 27b (electrode pad 29 [[19]]). Ceramic, etc., may be used as the material of package 27.